# Monthly LabAdviser update: 25/10 2012

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| Updated Subject | Contributer | Link to the update pages |
| Deposition of Silicon oxide | Katharina Nilson @danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Oxide> |
| Optical microscopes | Pernille Voss Larsen@ Danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Optical_microscope> |
| **Nanoman AFM** | Jesper Handberg@Danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/AFM:_Atomic_Force_Microscopy> |
| **LPCVD polysilicon** | Pernille Voss Larsen@Danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_polysilicon/Deposition_of_polysilicon_using_LPCVD> |
| **IBE**  Magnetic stack etch.  Endpoint detection with SIMS. | Kristian Hagsted Rasmussen @Nanotech | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/IBE%E2%81%84IBSD_Ionfab_300/IBE_magnetic_stack_etch> |
| **LPCVD nitride** | Mikkel M. Dysseholm @ Danchip **Perville V. Larsen @ Danchip** | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/B2_Furnace_LPCVD_Nitride>  <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Silicon_Nitride/Deposition_of_Silicon_Nitride_using_LPCVD> |
| Deposition of copper | Katharina Nilson@Danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Copper>  <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Multisource_PVD/Cu>  <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Multisource_PVD> |
| Dektak XTA new stulus profiler | Katharina Nilson@Danchip | <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Profiler>  <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Topographic_measurement>  <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Stress_measurement> |
| RIE1 and RIE2 “mask load affects the results” | Pernille V. Larsen @ Danchip | <http://labadviser.danchip.dtu.dk/index.php?title=Specific_Process_Knowledge/Etch/Etching_of_Silicon/Si_etch_using_RIE1_or_RIE2/Specific_Process_Knowledge/Etch/Etching_of_Silicon/Si_etch_using_RIE1_or_RIE2/RIE1_Travka_results&rcid=7219>  <http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon/Si_etch_using_RIE1_or_RIE2> |